IN THE CLAIMS:

Please amend the claims as follows.

1. (Original) A manufacturing method of an optical device, comprising the steps of:

coating a substrate with a resin thin film having a glass-transition temperature that is higher than 200°C;

controlling a temperature of the resin thin film to a temperature that is higher than the glass-transition temperature of the resin thin film and lower than a thermal decomposition starting temperature of the resin thin film;

pressing a die having an inverted micro-asperity pattern against the resin thin film in a state that the temperature of the resin thin film is controlled so as to be higher than the glass-transition temperature and lower than the thermal decomposition starting temperature; and

separating the die from the resin thin film after cooling the resin thin film so that the temperature of the resin thin film becomes lower than the glass-transition termperature,

whereby a micro-asperity pattern is formed on a surface of the resin thin film.

2. (Original) A manufacturing method of an optical device, comprising the steps of:

coating a substrate with a resin thin film in which polymerization reaction has not occurred yet substantially;

controlling a temperature of the resin thin film to a temperature that is lower than a polymerization reaction starting temperature of the resin thin film;

pressing a die having an inverted micro-asperity pattern against the resin thin film and separating the die from the resin thin film in a state that the temperature of the resin thin film is controlled so as to be lower than the polymerization reaction starting temperature; and

heating the resin thin film so that the temperature of the resin thin film becomes higher than the polymerization reaction starting temperature and lower than a glass-transition temperature of the resin thin film,

whereby a micro-asperity pattern is formed on a surface of the resin thin film.

3. (Original) The manufacturing method according to claim 1, wherein the die pressing step is executed plural times on the resin thin film.

4. (Original) The manufacturing method according to claim 2, wherein the die pressing step is executed plural times on the resin thin film.

5. (Original) The manufacturing method according to claim 1, further comprising the step of making adjustments by causing a relative movement between the substrate and the die so that a substrate-side alignment mark provided on the substrate coincides with a reference position on the die side.

6. - 29. (Canceled)

30. (Original) A manufacturing method of a reflection plate, comprising the steps of:

forming thin-film liquid crystal driving elements or wiring contacts on a substrate;

coating the substrate with a resin thin film having a glass-transition temperature that is higher than 200°C;

controlling a temperature of the resin thin film to a temperature that is higher than the glass-transition temperature of the resin thin film and lower than a thermal decomposition starting temperature of the resin thin film;

pressing a die having an inverted micro-asperity pattern against the resin thin film in a state that the temperature of the resin thin film is controlled so as to be higher than the glass-transition temperature and lower than the thermal decomposition starting temperature;

separating the die from the resin thin film after cooling the resin thin film so that the temperature of the resin thin film becomes lower than the glass-transition temperature;

heating the resin substrate so that the temperature of the resin thin film becomes higher than or equal to a polymerization reaction starting temperature of the resin thin film, whereby a micro-asperity pattern is formed on a surface of the resin thin film; and

forming a reflection film and an alignment film on the micro-asperity pattern.

31. (Canceled)